

488696-2026 - Kompetizzjoni

L-Irlanda – Tagħmir tal-laboratorju, ottiku u ta' preċiżjoni (minbarra nuċċalijiet) – LA3215C-UCC-CFT for the Supply of a Suite of Plasma Etcher and Plasma Deposition Tools, 4 Lots

OJ S 134/2026 15/07/2026

Avviż tal-kuntratt jew tal-konċessjoni – reġim standard - Avviż tal-bidla

Provvisti

1. Xerrej

1.1. Xerrej

Isem uffiċjali: Education Procurement Service (EPS)

Email: info@educationprocurementservice.ie

Tip legali tax-xerrej: Korp irregolat bil-liġi pubblika

Attività tal-awtorità kontraenti: Servizzi publiċi ġenerali

2. Proċedura

2.1. Proċedura

Titlu: LA3215C-UCC-CFT for the Supply of a Suite of Plasma Etcher and Plasma Deposition Tools, 4 Lots

Deskrizzjoni: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork. The new plasma tools will enhance the capabilities at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Identifikatur tal-proċedura: a024c275-b92f-48d9-83b8-52aa370660c8

Tip ta' proċedura: Miftuħa

Il-proċedura hija aċċellerata: Ie

2.1.1. Għan

Natura tal-kuntratt: Provvisti

Klassifikazzjoni prinċipali (cpv): 38000000 Tagħmir tal-laboratorju, ottiku u ta' preċiżjoni (minbarra nuċċalijiet)

2.1.2. Post tal-prestazzjoni

Sottodivizjoni tal-pajjiż (NUTS): South-East (IE052)

Pajjiż: L-Irlanda

2.1.3. Valur

Valur stmat mingħajr VAT: 3 300 000,00 EUR

2.1.4. Informazzjoni ġenerali

Bażi legali:

Direttiva 2014/24/UE

2.1.5. Termini tal-akkwist

Termini tas-sottomissjoni:

Numru massimu ta' lottijiet li għalihom offerent wieħed jista' jissottometti offerti: 4

2.1.6. Raġunijiet għall-esklużjoni

Sors tal-motivi għall-eżklussjoni: Dokument tal-Akkwist

5. Lott

5.1. Lott: LOT-0001

Titlu: Plasma Etcher ,Silicon ,Dielectrics

Deskrizzjoni: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork. The new plasma tools will enhance the capabilities at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Identifikatur intern: 1

5.1.1. Għan

Natura tal-kuntratt: Provvisti

Klassifikazzjoni prinċipali (cpv): 38000000 Tagħmir tal-laboratorju, ottiku u ta' preċiżjoni (minbarra nuċċalijiet)

5.1.2. Post tal-prestazzjoni

Sottodivizjoni tal-pajjiż (NUTS): South-East (IE052)

Pajjiż: L-Irlanda

5.1.3. Tul ta' żmien stmat

Tul ta' żmien: 48 Xhur

5.1.5. Valur

Valur stmat mingħajr VAT: 3 300 000,00 EUR

5.1.6. Informazzjoni ġenerali

Parteċipazzjoni riżervata:

Il-parteċipazzjoni mhijiex riżervata.

Proġett ta' akkwist mhux iffinanzjat mill-Fondi tal-UE

L-akkwist huwa kopert mill-Ftehim dwar l-Akkwisti Pubbliċi (GPA): iva

5.1.7. Akkwist strateġiku

Għan tal-akkwist strateġiku: Ebda akkwist strateġiku

5.1.9. Kriterji tal-għażla

Sors tal-kriterji ta' għażla: Dokument tal-Akkwist

5.1.11. Dokumenti tal-akkwist

Lingwi li bihom id-dokumenti tal-akkwist huma disponibbli uffiċjalment: Ingliż

Lingwi li bihom id-dokumenti tal-akkwist (jew partijiet minnhom) huma disponibbli mhux uffiċjalment: Ingliż

Skadenza biex tintalab informazzjoni addizzjonali: 07/07/2026 12:00:00 (UTC+01:00) Hin tal-Ewropa Ċentrali, Hin tas-sajf tal-Ewropa tal-Punent

Indirizz tad-dokumenti tal-akkwist: <https://www.etenders.gov.ie/epps/cft/listContractDocuments.do?resourceId=8424094>

5.1.12. Termini tal-akkwist

Termini tas-sottomissjoni:

Sottomissjoni elettronika: Meħtieġa

Indirizz għas-sottomissjoni: <https://www.etenders.gov.ie/epps/cft/viewTenders.do?resourceId=8424094>

Lingwi li bihom jistgħu jiġu sottomessi offerti jew talbiet għall-parteċipazzjoni: Ingliż

Katalogu elettroniku: Mhux permessa

L-offerenti jistgħu jifgħu aktar minn offerta waħda: Permessa

Skadenza biex jintlaqgħu l-offerti: 24/07/2026 12:00:00 (UTC+01:00) Hin tal-Ewropa Ċentrali, Hin tas-sajf tal-Ewropa tal-Punent

Perjodu waqt li l-offerta għandha tibqa' valida: 180 Jiem

Informazzjoni dwar il-ftuħ pubbliku:

Data tal-ftuħ: 24/07/2026 12:30:00 (UTC+01:00) Hin tal-Ewropa Ċentrali, Hin tas-sajf tal-Ewropa tal-Punent

Post: <https://www.etenders.gov.ie/epps/cft/prepareViewCfTWS.do?resourceId=8424094>

Termini tal-kuntratt:

L-eżekuzzjoni tal-kuntratt għandha titwettaq fil-qafas ta' programmi ta' impjiegi protetti: Għadu mhux magħruf

Fatturazzjoni elettronika: Meħtieġa

Se tintuża l-ordni elettronika: le
Se jintuża l-pagament elettroniku: le

5.1.15. Tekniki

Ftehim qafas:

Ebda ftehim ta' qafas

Informazzjoni dwar is-sistema dinamika tax-xiri:

Ebda sistema dinamika ta' xiri

5.1.16. Aktar informazzjoni, medjazzjoni u riežami

Organizzazzjoni tar-riežami: The High Court of Ireland

Organizzazzjoni li tipprovdi aċċess offline għad-dokumenti tal-akkwist: Education Procurement Service (EPS)

Organizzazzjoni li tipprovdi iktar informazzjoni dwar proċeduri tar-riežami: The High Court of Ireland

Organizzazzjoni li tirċievi t-talbiet għall-parteeċipazzjoni: Education Procurement Service (EPS)

Organizzazzjoni li tipproċessa l-offerti: Education Procurement Service (EPS)

5.1. Lott: LOT-0002

Titlu: Plasma Etcher ,Metals ,Piezoelectrics

Deskrizzjoni: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork. The new plasma tools will enhance the capabilities at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Identifikatur intern: 2

5.1.1. Għan

Natura tal-kuntratt: Provvisti

Klassifikazzjoni prinċipali (cpv): 38000000 Tagħmir tal-laboratorju, ottiku u ta' preċiżjoni (minbarra nuċċalijiet)

5.1.2. Post tal-prestazzjoni

Sottodivizjoni tal-pajjiż (NUTS): South-East (IE052)

Pajjiż: L-Irlanda

5.1.3. Tul ta' żmien stmat

Tul ta' żmien: 48 Xhur

5.1.5. Valur

Valur stmat mingħajr VAT: 3 300 000,00 EUR

5.1.6. Informazzjoni ġenerali

Parteċipazzjoni riżervata:

Il-parteċipazzjoni mhijiex riżervata.

Proġett ta' akkwist mhux iffinanzjat mill-Fondi tal-UE

L-akkwist huwa kopert mill-Ftehim dwar l-Akkwisti Pubbliċi (GPA): iva

5.1.7. Akkwist strateġiku

Għan tal-akkwist strateġiku: Ebda akkwist strateġiku

5.1.9. Kriterji tal-għażla

Sors tal-kriterji ta' għażla: Dokument tal-Akkwist

5.1.11. Dokumenti tal-akkwist

Lingwi li bihom id-dokumenti tal-akkwist huma disponibbli uffiċjalment: Ingliż

Lingwi li bihom id-dokumenti tal-akkwist (jew partijiet minnhom) huma disponibbli mhux uffiċjalment: Ingliż

Skadenza biex tintalab informazzjoni addizzjonali: 07/07/2026 12:00:00 (UTC+01:00) Hin tal-Ewropa Ċentrali, Hin tas-sajf tal-Ewropa tal-Punent

Indirizz tad-dokumenti tal-akkwist: <https://www.etenders.gov.ie/epps/cft/listContractDocuments.do?resourceId=8424094>

5.1.12. Termini tal-akkwist

Termini tas-sottomissjoni:

Sottomissjoni elettronika: Meħtieġa

Indirizz għas-sottomissjoni: <https://www.etenders.gov.ie/epps/cft/viewTenders.do?resourceId=8424094>

Lingwi li bihom jistgħu jiġu sottomessi offerti jew talbiet għall-parteċipazzjoni: Ingliż

Katalogu elettroniku: Mhux permessa

L-offerenti jistgħu jifgħu aktar minn offerta waħda: Permissa

Skadenza biex jintlaqgħu l-offerti: 24/07/2026 12:00:00 (UTC+01:00) Hin tal-Ewropa Ċentrali, Hin tas-sajf tal-Ewropa tal-Punent

Perjodu waqt li l-offerta għandha tibqa' valida: 180 Jiem

Informazzjoni dwar il-ftuħ pubbliku:

Data tal-ftuħ: 24/07/2026 12:30:00 (UTC+01:00) Hin tal-Ewropa Ċentrali, Hin tas-sajf tal-Ewropa tal-Punent

Post: <https://www.etenders.gov.ie/epps/cft/prepareViewCfTWS.do?resourceId=8424094>

Termini tal-kuntratt:

L-eżekuzzjoni tal-kuntratt għandha titwettaq fil-qafas ta' programmi ta' impjegi protetti: Għadu mhux magħruf

Fatturazzjoni elettronika: Meħtieġa

Se tintuża l-ordni elettronika: Ie

Se jintuża l-pagament elettroniku: Ie

5.1.15. Tekniki

Ftehim qafas:

Ebda ftehim ta' qafas

Informazzjoni dwar is-sistema dinamika tax-xiri:

Ebda sistema dinamika ta' xiri

5.1.16. Aktar informazzjoni, medjazzjoni u riežami

Organizzazzjoni tar-riežami: The High Court of Ireland

Organizzazzjoni li tipprovdi aċċess offline għad-dokumenti tal-akkwist: Education Procurement Service (EPS)

Organizzazzjoni li tipprovdi iktar informazzjoni dwar proċeduri tar-riežami: The High Court of Ireland

Organizzazzjoni li tirċievi t-talbiet għall-partekipazzjoni: Education Procurement Service (EPS)

Organizzazzjoni li tipproċessa l-offerti: Education Procurement Service (EPS)

5.1. Lott: LOT-0003

Titlu: Plasma Etcher ,Slow and Controllable Rate ,Atomic Layer Etch for Silicon , Dielectrics

Deskrizzjoni: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork.

The new plasma tools will enhance the capabilities at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Identifikatur intern: 3

5.1.1. Għan

Natura tal-kuntratt: Provvisti

Klassifikazzjoni prinċipali (cpv): 38000000 Tagħmir tal-laboratorju, ottiku u ta' preċiżjoni (minbarra nuċċalijiet)

5.1.2. Post tal-prestazzjoni

Sottodivizjoni tal-pajjiż (NUTS): South-East (IE052)

Pajjiż: L-Irlanda

5.1.3. Tul ta' żmien stmat

Tul ta' żmien: 48 Xhur

5.1.5. Valur

Valur stmat mingħajr VAT: 3 300 000,00 EUR

5.1.6. Informazzjoni ġenerali

Parteċipazzjoni riżervata:

Il-parteċipazzjoni mhijiex riżervata.

Proġett ta' akkwist mhux iffinanzjat mill-Fondi tal-UE

L-akkwist huwa kopert mill-Ftehim dwar l-Akkwisti Pubbliċi (GPA): iva

5.1.7. Akkwist strateġiku

Għan tal-akkwist strateġiku: Ebda akkwist strateġiku

5.1.9. Kriterji tal-għażla

Sors tal-kriterji ta' għażla: Dokument tal-Akkwist

5.1.11. Dokumenti tal-akkwist

Lingwi li bihom id-dokumenti tal-akkwist huma disponibbli uffiċjalment: Ingliż

Lingwi li bihom id-dokumenti tal-akkwist (jew partijiet minnhom) huma disponibbli mhux uffiċjalment: Ingliż

Skadenza biex tintalab informazzjoni addizzjonali: 07/07/2026 12:00:00 (UTC+01:00) Ħin tal-Ewropa Ċentrali, Ħin tas-sajf tal-Ewropa tal-Punent

Inderizz tad-dokumenti tal-akkwist: <https://www.etenders.gov.ie/epps/cft/listContractDocuments.do?resourceId=8424094>

5.1.12. Termini tal-akkwist

Termini tas-sottomissjoni:

Sottomissjoni elettronika: Meħtieġa

Inderizz għas-sottomissjoni: <https://www.etenders.gov.ie/epps/cft/viewTenders.do?resourceId=8424094>

Lingwi li bihom jistgħu jiġu sottomessi offerti jew talbiet għall-parteċipazzjoni: Ingliż

Katalogu elettroniku: Mhux permessa

L-offerenti jistgħu jifgħu aktar minn offerta waħda: Permissa

Skadenza biex jintlaqgħu l-offerti: 24/07/2026 12:00:00 (UTC+01:00) Ħin tal-Ewropa Ċentrali, Ħin tas-sajf tal-Ewropa tal-Punent

Perjodu waqt li l-offerta għandha tibqa' valida: 180 Jiem

Informazzjoni dwar il-ftuħ pubbliku:

Data tal-ftuħ: 24/07/2026 12:30:00 (UTC+01:00) Ħin tal-Ewropa Ċentrali, Ħin tas-sajf tal-Ewropa tal-Punent

Post: <https://www.etenders.gov.ie/epps/cft/prepareViewCfTWS.do?resourceId=8424094>

Termini tal-kuntratt:

L-eżekuzzjoni tal-kuntratt għandha titwettaq fil-qafas ta' programmi ta' impjiegi protetti: Għadu mhux magħruf

Fatturazzjoni elettronika: Meħtieġa

Se tintuża l-ordni elettronika: Ie

Se jintuża l-pagament elettroniku: Ie

5.1.15. Tekniki

Ftehim qafas:

Ebda ftehim ta' qafas

Informazzjoni dwar is-sistema dinamika tax-xiri:

Ebda sistema dinamika ta' xiri

5.1.16. Aktar informazzjoni, medjazzjoni u rieżami

Organizzazzjoni tar-rieżami: The High Court of Ireland

Organizzazzjoni li tipprovdi aċċess offline għad-dokumenti tal-akkwist: Education Procurement Service (EPS)

Organizzazzjoni li tipprovdi iktar informazzjoni dwar proċeduri tar-rieżami: The High Court of Ireland

Organizzazzjoni li tirċievi t-talbiet għall-partecipazzjoni: Education Procurement Service (EPS)

Organizzazzjoni li tipproċessa l-offerti: Education Procurement Service (EPS)

5.1. Lott: LOT-0004

Titlu: Plasma Deposition ,PECVD

Deskrizzjoni: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork. The new plasma tools will enhance the capabilities at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Identifikatur intern: 4

5.1.1. Għan

Natura tal-kuntratt: Provvisti

Klassifikazzjoni prinċipali (cpv): 38000000 Tagħmir tal-laboratorju, ottiku u ta' preċiżjoni (minbarra nuċċalijiet)

5.1.2. Post tal-prestazzjoni

Sottodivizjoni tal-pajjiż (NUTS): South-East (IE052)

Pajjiż: L-Irlanda

5.1.3. Tul ta' żmien stmat

Tul ta' żmien: 48 Xhur

5.1.5. Valur

Valur stmat mingħajr VAT: 3 300 000,00 EUR

5.1.6. Informazzjoni ġenerali

Partecipazzjoni riżervata:

Il-partecipazzjoni mhijiex riżervata.

Proġett ta' akkwist mhux iffinanzjat mill-Fondi tal-UE

L-akkwist huwa kopert mill-Ftehim dwar l-Akkwisti Pubbliċi (GPA): iva

5.1.7. Akkwist strateġiku

Għan tal-akkwist strateġiku: Ebda akkwist strateġiku

5.1.9. Kriterji tal-għażla

Sors tal-kriterji ta' għażla: Dokument tal-Akkwist

5.1.11. Dokumenti tal-akkwist

Lingwi li bihom id-dokumenti tal-akkwist huma disponibbli uffiċjalment: Ingliż

Lingwi li bihom id-dokumenti tal-akkwist (jew partijiet minnhom) huma disponibbli mhux uffiċjalment: Ingliż

Skadenza biex tintalab informazzjoni addizzjonali: 07/07/2026 12:00:00 (UTC+01:00) H'in tal-Ewropa Ċentrali, H'in tas-sajf tal-Ewropa tal-Punent

Indirizz tad-dokumenti tal-akkwist: <https://www.etenders.gov.ie/epps/cft/listContractDocuments.do?resourceId=8424094>

5.1.12. Termini tal-akkwist

Termini tas-sottomissjoni:

Sottomissjoni elettronika: Meħtieġa

Indirizz għas-sottomissjoni: <https://www.etenders.gov.ie/epps/cft/viewTenders.do?resourceId=8424094>

Lingwi li bihom jistgħu jiġu sottomessi offerti jew talbiet għall-parteciġazzjoni: Ingliż

Katalogu elettroniku: Mhux permessa

L-offerenti jistgħu jittgħu aktar minn offerta waħda: Permissa

Skadenza biex jintlaqgħu l-offerti: 24/07/2026 12:00:00 (UTC+01:00) H'in tal-Ewropa Ċentrali, H'in tas-sajf tal-Ewropa tal-Punent

Perjodu waqt li l-offerta għandha tibqa' valida: 180 Jiem

Informazzjoni dwar il-ftuħ pubbliku:

Data tal-ftuħ: 24/07/2026 12:30:00 (UTC+01:00) H'in tal-Ewropa Ċentrali, H'in tas-sajf tal-Ewropa tal-Punent

Post: <https://www.etenders.gov.ie/epps/cft/prepareViewCfTWS.do?resourceId=8424094>

Termini tal-kuntratt:

L-eżekuzzjoni tal-kuntratt għandha titwettag fil-qafas ta' programmi ta' impjiegi protetti: Għadu mhux magħruf

Fatturazzjoni elettronika: Meħtieġa

Se tintuża l-ordni elettronika: Ie

Se jintuża l-pagament elettroniku: Ie

5.1.15. Tekniki

Ftehim qafas:

Ebda ftehim ta' qafas

Informazzjoni dwar is-sistema dinamika tax-xiri:

Ebda sistema dinamika ta' xiri

5.1.16. Aktar informazzjoni, medjazzjoni u rieżami

Organizzazzjoni tar-rieżami: The High Court of Ireland

Organizzazzjoni li tipprovdi aċċess offline għad-dokumenti tal-akkwist: Education Procurement Service (EPS)

Organizzazzjoni li tipprovdi iktar informazzjoni dwar proċeduri tar-rieżami: The High Court of Ireland

Organizzazzjoni li tirċievi t-talbiet għall-parteciġazzjoni: Education Procurement Service (EPS)

8. Organizzazzjonijiet

8.1. ORG-0001

Isem uffiċjali: Education Procurement Service (EPS)

Numru tar-reġistrazzjoni: IE 6609370 G

Indirizz postali: Castletroy Limerick

Belt: Limerick

Kodiċi postali: V94 DK53

Sottodivizjoni tal-pajjiż (NUTS): Mid-West (IE051)

Pajjiż: L-Irlanda

Email: info@educationprocurementservice.ie

Telefown: 000

Indirizz tal-internet: <https://www.educationprocurementservice.ie/>

Profil tax-xerrej: <https://www.educationprocurementservice.ie/>

Rwoli ta' din l-organizzazzjoni:

Xerrej

Organizzazzjoni li tipprovdi aċċess offline għad-dokumenti tal-akkwist

Organizzazzjoni li tirċievi t-talbiet għall-partecipazzjoni

Organizzazzjoni li tipproċessa l-offerti

8.1. ORG-0002

Isem uffiċjali: The High Court of Ireland

Numru tar-reġistrazzjoni: The High Court of Ireland

Dipartiment: The High Court of Ireland

Indirizz postali: Four Courts, Inns Quay, Dublin 7

Belt: Dublin

Kodiċi postali: D07 WDX8

Sottodivizjoni tal-pajjiż (NUTS): Dublin (IE061)

Pajjiż: L-Irlanda

Email: HighCourtCentralOffice@courts.ie

Telefown: +353 1 8886000

Rwoli ta' din l-organizzazzjoni:

Organizzazzjoni tar-rieżami

Organizzazzjoni li tipprovdi iktar informazzjoni dwar proċeduri tar-rieżami

8.1. ORG-0003

Isem uffiċjali: European Dynamics S.A.

Numru tar-reġistrazzjoni: 002024901000

Dipartiment: European Dynamics S.A.

Belt: Athens

Kodiċi postali: 15125

Sottodivizjoni tal-pajjiż (NUTS): Βόρειος Τομέας Αθηνών (EL301)

Pajjiż: Il-Greċja

Email: eproc-esender@eurodyn.com

Telefown: +30 2108094500

Rwoli ta' din l-organizzazzjoni:

TED eSender

10. Bidla

Verżjoni tal-avviż preċedenti li għandu jinbidel

:

46fee6a2-f409-4cd6-80db-618a50fcc925-01

Raġuni ewlenija għall-bidla

:

Informazzjoni aġġornata

Informazzjoni dwar l-avviż

Identifikatur/verżjoni tal-avviż: 7a2067c1-5ebe-49f4-b53b-0f9595ac5fa3 - 02

Tip ta' formola: Kompetizzjoni

Tip ta' avviż: Avviż tal-kuntratt jew tal-konċessjoni – reġim standard

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